

IMT-TE1100B-UF B-STAGE ADHESIVE

IMT-TE1100B-UF is an unfilled version of IMT-TE1100B. This electrically and thermally non-conductive B-stage adhesive is designed for chip scale packages. This B-stage adhesive does not contain any prohibited and/or hazardous substances, is solventless and a 100% solid system. It complies to RoHS3, EU directive 2015/863 as well as Substances of Very High Concern (SVHC) published by ECHA.

IMT-TE1100B-UF is packed in syringes for use in automated, high speed dispensing equipment or in jar for printing method.

TYPICAL PROPERTIES*

Cure Conditions (Actual holding temperature & time) B Stage: 110°C for 30 mins
Post Cure: 150°C for 60 mins

Pot Life 4 days at room temperature
Shelf Life 12 months at -40°C

Physical Properties

Color Off white before cure & milky white after cure
Consistency Smooth, thixotropic paste
Specific Gravity 1.10
Viscosity @25°C, 10rpm 14,000cPs
Thixotropic Index, (1/10rpm) 3.5
Glass Transition Temperature 115°C
Shore D Hardness 85
Die Shear Strength > 15Kgf per 3.5x2mm chip on FR4 substrate
Operating Temperature -40°C to +150°C

Ionic Contents

Chloride, Cl- ≤ 600ppm
Bromine, Br- Not detected
PVC Not detected

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* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.